MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS



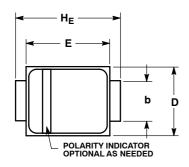
DATE 19 JUL 2012

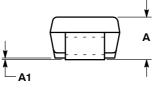
SMB CASE 403A-03 **ISSUE J**

SCALE 1:1 **Polarity Band**

Т

SCALE 1:1 Non-Polarity Band

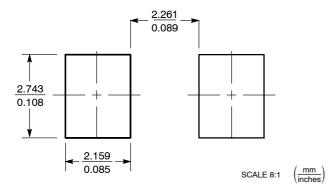




SOLDERING FOOTPRINT*

С

11



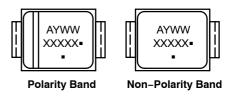
*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION & SHALL BE MEASURED WITHIN DIMENSION L1.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.95	2.30	2.47	0.077	0.091	0.097
A1	0.05	0.10	0.20	0.002	0.004	0.008
b	1.96	2.03	2.20	0.077	0.080	0.087
С	0.15	0.23	0.31	0.006	0.009	0.012
D	3.30	3.56	3.95	0.130	0.140	0.156
E	4.06	4.32	4.60	0.160	0.170	0.181
HE	5.21	5.44	5.60	0.205	0.214	0.220
L	0.76	1.02	1.60	0.030	0.040	0.063
L1	0.51 REF			0.020 REF		

GENERIC **MARKING DIAGRAM***



XXXXX = Specific Device Code

А = Assembly Location

= Year

.

Υ = Work Week WW

= Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

DOCUMENT NUMBER:	98ASB42669B	Electronic versions are uncontrolled except when		
STATUS:	ON SEMICONDUCTOR STANDARD	accessed directly from the Document Report versions are uncontrolled except when		
NEW STANDARD:		"CONTROLLED COPY" in red.		
DESCRIPTION:	SMB	РА	AGE 1 OF 2	



DOCUMENT NUMBER: 98ASB42669B

PAGE 2 OF 2

ISSUE REVISION					
		DATE			
E	ADDED NOMINAL VALUES, MARKING DIAGRAM AND SOLDERING FOOTPRINT. REQ. BY HONG XIAO.	03 AUG 2005			
F	UPDATED MAXIMUM DIMENSION LIMITS TO JEDEC STANDARDS. REQ. BY LOUIS TSAI.	30 NOV 2005			
G	ADDED NON-POLARITY BAND OPTION. CORRECTED DEVICE MARKING. REQ. BY D. TRUHITTE.	07 JUL 2008			
Н	MODIFIED DIMENSION A NOMINAL AND MAXIMUM VALUES. MODIFIED DIMEN- SION A1 MAXIMUM VALUES. REQ. BY D. KNUDSEN.	04 MAY 2011			
J	MODIFIED MAX A1 DIMENSIONS TO 0.20 MM & 0.008 INCH AND UPDATED A DIMENSIONS. REQ. BY D. KNUDSEN.	19 JUL 2012			
	1				

ON Semiconductor and with a registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other application in which the failure of the SCILLC product create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use persores that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.